

3A Avg.

65 Volts

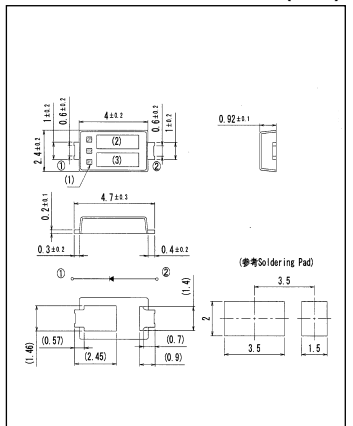
SBD

NA03QSA065

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	65	V
平均整流電流 Average Rectified Forward Current	$I_O$	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_a=27^\circ\text{C}^*$ $V_{RM}=30\text{V}$ 1.3 A
			$T_l=117^\circ\text{C}$ Ti:lead Temperature $V_{RM}=30\text{V}$ 3.0 A
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	4.71	A
サージ順電流 Surge Forward Current	$I_{FSM}$	60 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$	-40~+150	$^\circ\text{C}$
保存温度範囲 Storage Temperature Range	$T_{stg}$	-40~+150	$^\circ\text{C}$

■OUTLINE DRAWING(mm)



■APPROX. NET WEIGHT:0.03 g

■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$T_j=25^\circ\text{C}, V_{RM}=65\text{V}$	—	—	300	$\mu\text{A}$
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$T_j=25^\circ\text{C}, I_{FM}=3\text{A}$	—	—	0.61	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	—	—	130	$^\circ\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	13	$^\circ\text{C}/\text{W}$

\*プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands= 2.0 × 1.5 mm, 2.0 × 3.5 mm)

■定格・特性曲線

